

CHIP SIZE IMAGE SENSOR WIREBOND PACKAGE FABRICATION
METHOD

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ABSTRACT

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To form an image sensor package, a window is mounted above an active area on an upper surface of an image sensor. A noncritical region of the upper
10 surface of the image sensor is between the active area and bond pads of the image sensor. A lower surface of a step up ring is mounted above the noncritical region of the upper surface of the image sensor. An upper surface of the step up ring includes a plurality of
15 electrically conductive traces. Bond wires are formed between the bond pads of the image sensor and the electrically conductive traces on the upper surface of the step up ring. The step up ring is mounted so that the window is located in or adjacent a central aperture
20 of the step up ring. The central aperture of the step up ring is filled with an encapsulant to form an inner package body. An outer package body is formed by enclosing the bond pads and bond wires in an encapsulant.